1. A method comprising:

forming a heat transfer fin of a laminate of two different materials; and

permanently securing said fin to a heat conductive base.

2. The method of claim 1 wherein forming said fin includes forming a laminate of metallic and non-metallic material.

3. The method of claim 1 including securing said laminate to the base using crimping.

4. The method of claim 2 including adhesively bonding said metallic and non-metallic materials.

5. The method of claim 1 wherein forming a heat transfer fin includes forming a fin of a laminate of a metallic and a pyrolytic graphite material.

6. The method of claim 1 including forming the fin with an aspect ratio higher than 20:1.

7. The method of claim 5 including forming the fin with an aspect ratio of 60:1.

8. The method of claim 1 including securing heat transfer fin to an integrated circuit.

9. The method of claim 8 including securing said heat transfer fin to a microprocessor.

10. The method of claim 2 including forming the metallic and non-metallic material of equal thicknesses.

11. A heat sink comprising:

a heat sink fin including two different materials; and

a conductive base, said fin secured to said base.

12. The heat sink of claim 11 wherein one of said materials is metallic and the other is non-metallic.

13. The heat sink of claim 11 wherein said fin is crimped to said base.

14. The heat sink of claim 12 wherein said metallic and non-metallic materials are adhesively bonded.

15. The heat sink of claim 12 wherein said non-metallic material is a pyrolytic graphite material.

16. The heat sink of claim 11 wherein the fin aspect ratio is higher than 20:1.

17. The heat sink of claim 16 wherein the fin aspect ratio is 60:1.

18. The heat sink of claim 11 wherein said base is secured to an integrated circuit.

19. The heat sink of claim 18 wherein said integrated circuit is a microprocessor.

20. The heat sink of claim 11, said fin including a first sheet of metallic material and a second sheet of non-metallic material, said sheets being laminated together.

21. The heat sink of claim 20 wherein said first and second sheets are of equal thicknesses.

22. An integrated circuit comprising:

an integrated circuit chip; and

a heat sink secured to said chip, said heat sink including a heat transfer fin of a laminate of metallic and non-metallic material.

23. The circuit of claim 22 wherein said fin is crimped to said base.

24. The circuit of claim 22 wherein said metallic and non-metallic materials are adhesively bonded.

25. The circuit of claim 22 wherein said non-metallic material is a pyrolytic graphite material.

26. The circuit of claim 22 wherein the fin aspect ratio is higher than 20:1.

27. The circuit of claim 26 wherein the fin aspect ratio is 60:1.

28. The circuit of claim 22 wherein said base is secured to an integrated circuit.

29. The circuit of claim 28 wherein said integrated circuit chip is a microprocessor.

30. The circuit of claim 22 wherein said metallic and non-metallic material are of equal thicknesses.